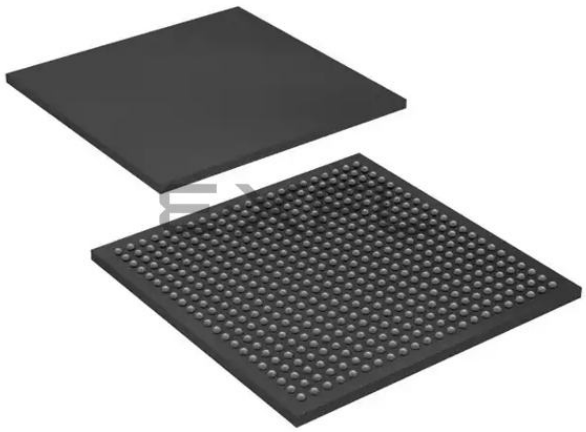

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	963
Number of Logic Elements/Cells	15408
Total RAM Bits	516096
Number of I/O	343
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce15f23c8l

Read or Write Clock Mode

Cyclone IV devices M9K memory blocks can implement read or write clock mode for FIFO and simple dual-port memories. In this mode, a write clock controls the data inputs, write address, and `wren` registers. Similarly, a read clock controls the data outputs, read address, and `rden` registers. M9K memory blocks support independent clock enables for both the read and write clocks.

When using read or write mode, if you perform a simultaneous read or write to the same address location, the output read data is unknown. If you require the output data to be a known value, use either single-clock mode, input clock mode, or output clock mode and choose the appropriate read-during-write behavior in the MegaWizard Plug-In Manager.

Single-Clock Mode

Cyclone IV devices M9K memory blocks can implement single-clock mode for FIFO, ROM, true dual-port, simple dual-port, and single-port memories. In this mode, you can control all registers of the M9K memory block with a single clock together with clock enable.

Design Considerations

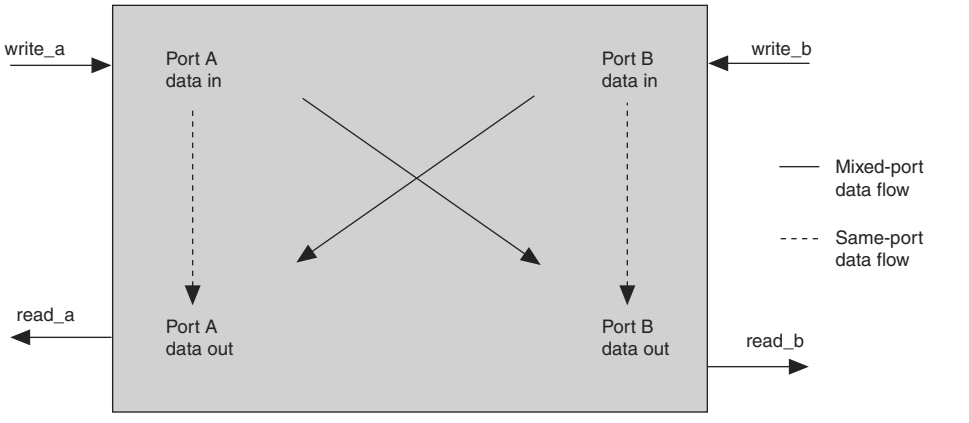
This section describes designing with M9K memory blocks.

Read-During-Write Operations

"Same-Port Read-During-Write Mode" on page 3–16 and "Mixed-Port Read-During-Write Mode" on page 3–16 describe the functionality of the various RAM configurations when reading from an address during a write operation at that same address.

There are two read-during-write data flows: same-port and mixed-port. Figure 3–13 shows the difference between these flows.

Figure 3–13. Cyclone IV Devices Read-During-Write Data Flow

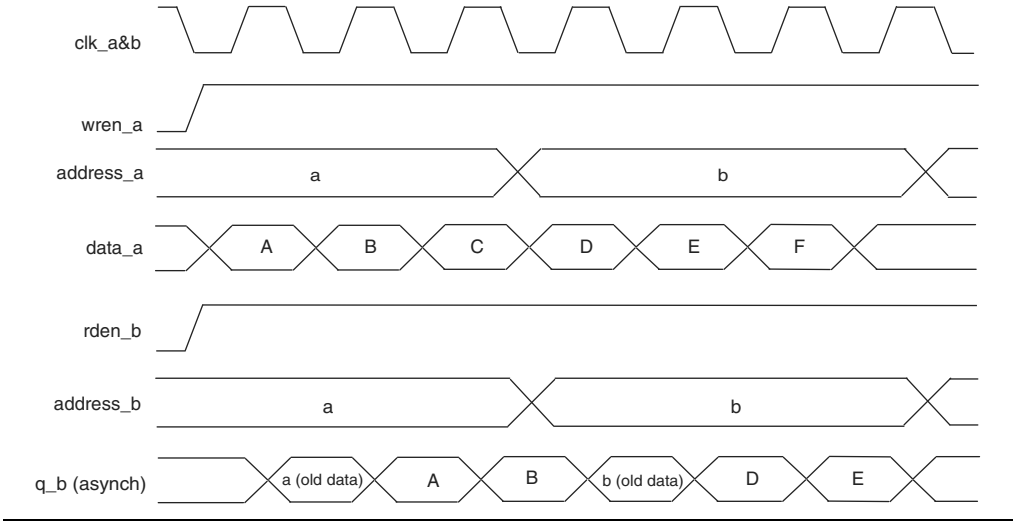


In this mode, you also have two output choices: **Old Data** mode or **Don't Care** mode. In **Old Data** mode, a read-during-write operation to different ports causes the RAM outputs to reflect the old data at that address location. In **Don't Care** mode, the same operation results in a "Don't Care" or unknown value on the RAM outputs.

For more information about how to implement the desired behavior, refer to the *RAM Megafunction User Guide*.

Figure 3–16 shows a sample functional waveform of mixed port read-during-write behavior for **Old Data** mode. In **Don't Care** mode, the old data is replaced with "Don't Care".

Figure 3–16. Mixed Port Read-During-Write: Old Data Mode



For mixed-port read-during-write operation with dual clocks, the relationship between the clocks determines the output behavior of the memory. If you use the same clock for the two clocks, the output is the old data from the address location. However, if you use different clocks, the output is unknown during the mixed-port read-during-write operation. This unknown value may be the old or new data at the address location, depending on whether the read happens before or after the write.

Conflict Resolution

When you are using M9K memory blocks in true dual-port mode, it is possible to attempt two write operations to the same memory location (address). Because there is no conflict resolution circuitry built into M9K memory blocks, this results in unknown data being written to that location. Therefore, you must implement conflict-resolution logic external to the M9K memory block.

Clock Switchover

The clock switchover feature allows the PLL to switch between two reference input clocks. Use this feature for clock redundancy or for a dual-clock domain application, such as a system that turns on the redundant clock if the previous clock stops running. Your design can automatically perform clock switchover when the clock is no longer toggling, or based on the user control signal, `clkswitch`.

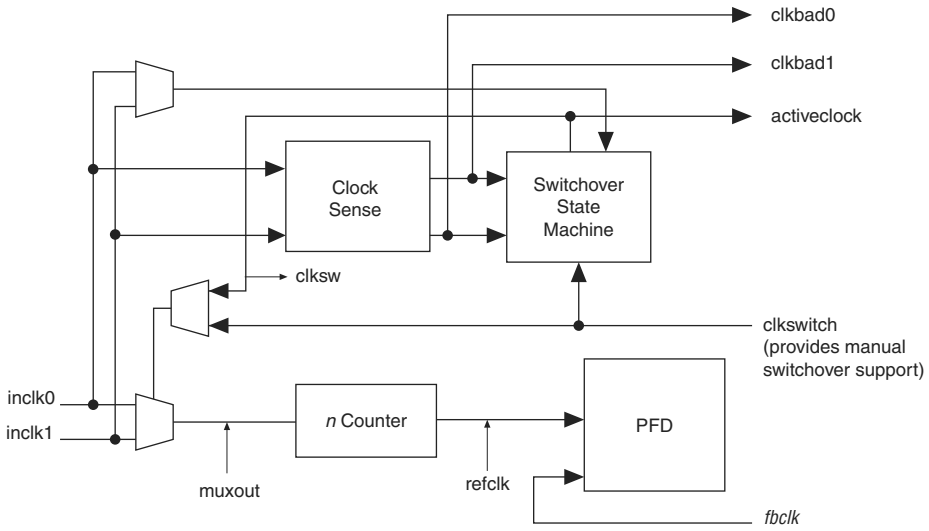
Automatic Clock Switchover

PLLs of Cyclone IV devices support a fully configurable clock switchover capability.

When the current reference clock is not present, the clock-sense block automatically switches to the backup clock for PLL reference. The clock switchover circuit also sends out three status signals—`clkbad0`, `clkbad1`, and `activeclock`—from the PLL to implement a custom switchover circuit. You can select a clock source at the backup clock by connecting it to the `inclk1` port of the PLL in your design.

Figure 5–17 shows the block diagram of the switchover circuit built into the PLL.

Figure 5–17. Automatic Clock Switchover Circuit



There are two ways to use the clock switchover feature:

- Use the switchover circuitry for switching from `inclk0` to `inclk1` running at the same frequency. For example, in applications that require a redundant clock with the same frequency as the reference clock, the switchover state machine generates a signal that controls the multiplexer select input shown in Figure 5–17. In this case, `inclk1` becomes the reference clock for the PLL. This automatic switchover can switch back and forth between the `inclk0` and `inclk1` clocks any number of times, when one of the two clocks fails and the other clock is available.
- Use the `clkswitch` input for user- or system-controlled switch conditions. This is possible for same-frequency switchover or to switch between inputs of different frequencies. For example, if `inclk0` is 66 MHz and `inclk1` is 200 MHz, you must control the switchover because the automatic clock-sense circuitry cannot monitor primary and secondary clock frequencies with a frequency difference of more than

- Low time count = 1 cycle
- `rselodd` = 1 effectively equals:
  - High time count = 1.5 cycles
  - Low time count = 1.5 cycles
  - Duty cycle = (1.5/3)% high time count and (1.5/3)% low time count

Scan Chain Description

Cyclone IV PLLs have a 144-bit scan chain.

Table 5–7 lists the number of bits for each component of the PLL.

Table 5–7. Cyclone IV PLL Reprogramming Bits

Block Name	Number of Bits		
	Counter	Other	Total
C4 *(1)*	16	2 *(2)*	18
C3	16	2 *(2)*	18
C2	16	2 *(2)*	18
C1	16	2 *(2)*	18
C0	16	2 *(2)*	18
M	16	2 *(2)*	18
N	16	2 *(2)*	18
Charge Pump	9	0	9
Loop Filter *(3)*	9	0	9
Total number of bits:			144

Notes to Table 5–7:

(1) LSB bit for C4 low-count value is the first bit shifted into the scan chain.

(2) These two control bits include `rbypass`, for bypassing the counter, and `rselodd`, to select the output clock duty cycle.

(3) MSB bit for loop filter is the last bit shifted into the scan chain.

Figure 5–24 shows the scan chain order of the PLL components.

Figure 5–24. PLL Component Scan Chain Order

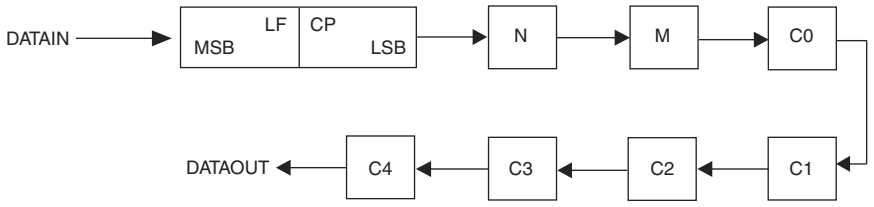
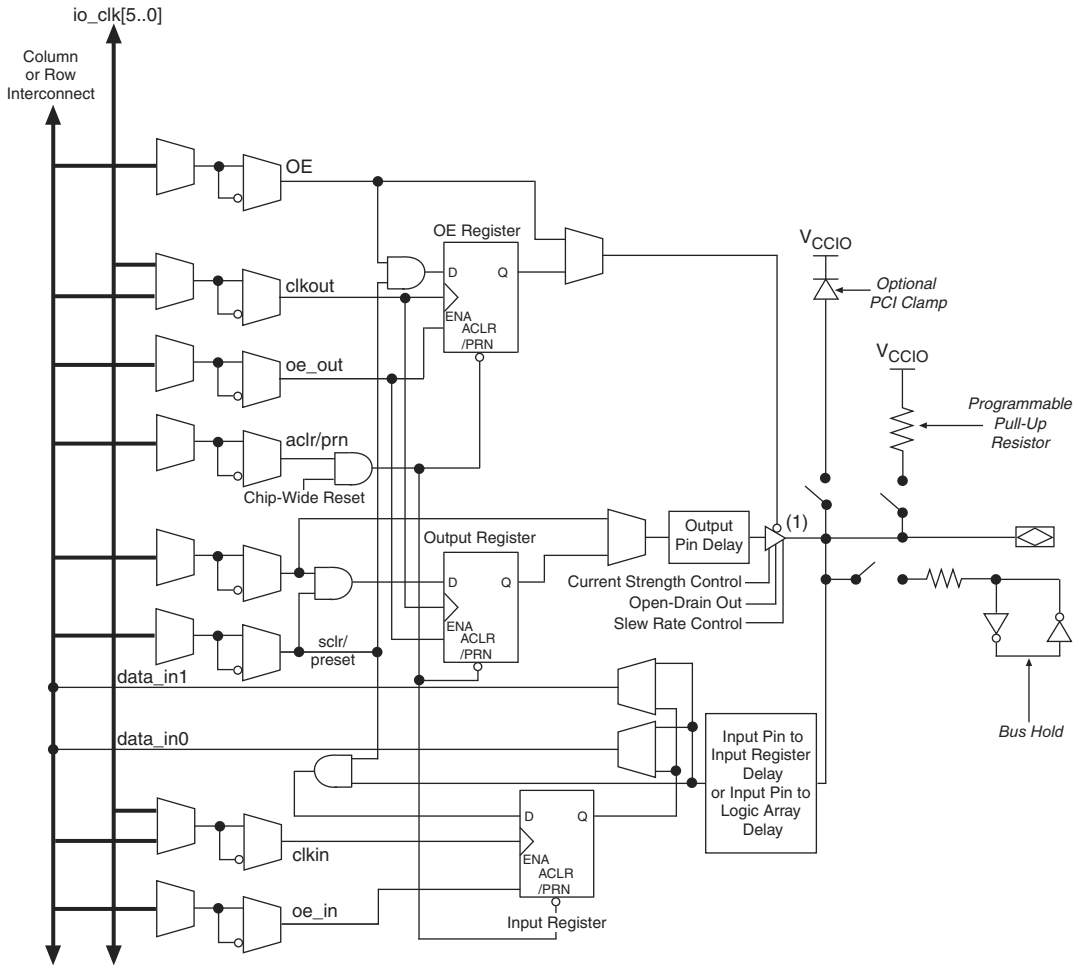


Figure 6–1 shows the Cyclone IV devices IOE structure for single data rate (SDR) operation.

Figure 6–1. Cyclone IV IOEs in a Bidirectional I/O Configuration for SDR Mode



Note to Figure 6–1:

(1) Tri-state control is not available for outputs configured with true differential I/O standards.

I/O Element Features

The Cyclone IV IOE offers a range of programmable features for an I/O pin. These features increase the flexibility of I/O utilization and provide a way to reduce the usage of external discrete components, such as pull-up resistors and diodes.

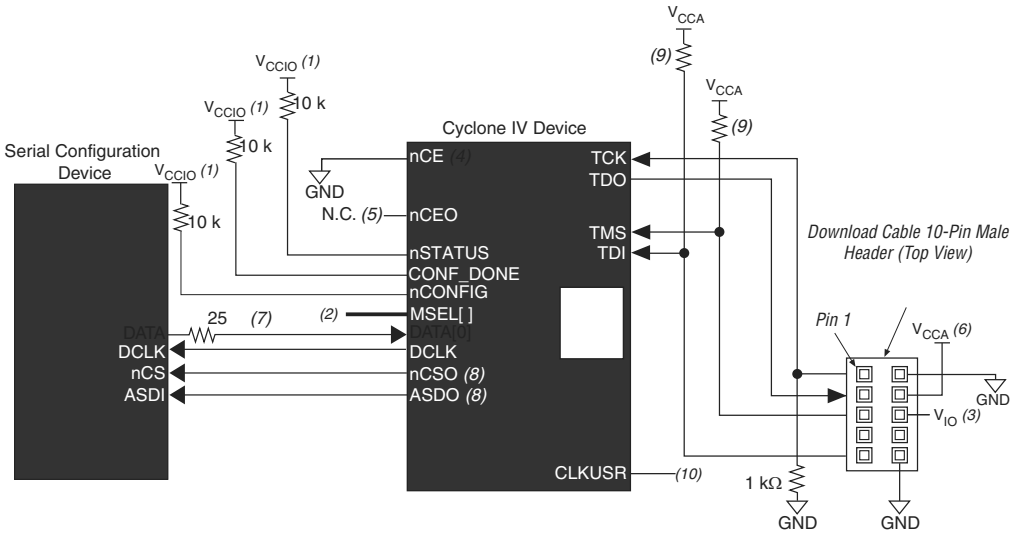
Programmable Current Strength

The output buffer for each Cyclone IV I/O pin has a programmable current strength control for certain I/O standards.

The LVTTL, LVCMOS, SSTL-2 Class I and II, SSTL-18 Class I and II, HSTL-18 Class I and II, HSTL-15 Class I and II, and HSTL-12 Class I and II I/O standards have several levels of current strength that you can control.

If you configure a master device with an SFL design, the master device enters user mode even though the slave devices in the multiple device chain are not being configured. The master device enters user mode with a SFL design even though the CONF_DONE signal is externally held low by the other slave devices in chain. Figure 8–29 shows the JTAG configuration of a single Cyclone IV device with a SFL design.

Figure 8–29. Programming Serial Configuration Devices In-System Using the JTAG Interface



Notes to Figure 8–29:

(1) Connect the pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect MSEL for AS configuration schemes, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. The V_{IO} must match the V_{CCA} of the device. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the ByteBlasterMV download cable, this pin is a no connect. When using USB-Blaster, ByteBlaster II, and EthernetBlaster cables, this pin is connected to nCE when it is used for AS programming, otherwise it is a no connect.

(4) You must connect the nCE pin to GND or driven low for successful JTAG configuration.

(5) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(6) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5- V V_{CCA} supply. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

(7) Connect the series resistor at the near end of the serial configuration device.

(8) These pins are dual-purpose I/O pins. The nCSO pin functions as FLASH_nCE pin in AP mode. The ASDO pin functions as DATA[1] pin in AP and FPP modes.

(9) Resistor value can vary from 1 kΩ to 10 kΩ.

(10) Only Cyclone IV GX devices have an option to select CLKUSR (40 MHz maximum) as the external clock source for DCLK.

ISP of the Configuration Device

In the second stage, the SFL design in the master device allows you to write the configuration data for the device chain into the serial configuration device with the Cyclone IV device JTAG interface. The JTAG interface sends the programming data for the serial configuration device to the Cyclone IV device first. The Cyclone IV device then uses the ASMI pins to send the data to the serial configuration device.

Table 8–21 lists the optional configuration pins. If you do not enable these optional configuration pins in the Quartus II software, they are available as general-purpose user I/O pins. Therefore, during configuration, these pins function as user I/O pins and are tri-stated with weak pull-up resistors.

Table 8–21. Optional Configuration Pins

Pin Name	User Mode	Pin Type	Description
CLKUSR	N/A if option is on. I/O if option is off.	Input	Optional user-supplied clock input synchronizes the initialization of one or more devices. This pin is enabled by turning on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software. In AS configuration for Cyclone IV GX devices, you can use this pin as an external clock source to generate the DCLK by changing the clock source option in the Quartus II software in the **Configuration** tab of the **Device and Pin Options** dialog box.
INIT_DONE	N/A if option is on. I/O if option is off.	Output open-drain	Status pin is used to indicate when the device has initialized and is in user-mode. When nCONFIG is low, the INIT_DONE pin is tri-stated and pulled high due to an external 10-kΩ pull-up resistor during the beginning of configuration. After the option bit to enable INIT_DONE is programmed into the device (during the first frame of configuration data), the INIT_DONE pin goes low. When initialization is complete, the INIT_DONE pin is released and pulled high and the device enters user mode. Thus, the monitoring circuitry must be able to detect a low-to-high transition. This pin is enabled by turning on the **Enable INIT_DONE output** option in the Quartus II software. The functionality of this pin changes if the **Enable OCT_DONE** option is enabled in the Quartus II software. This option controls whether the INIT_DONE signal is gated by the OCT_DONE signal, which indicates the power-up on-chip termination (OCT) calibration is complete. If this option is turned off, the INIT_DONE signal is not gated by the OCT_DONE signal.
DEV_OE	N/A if option is on. I/O if option is off.	Input	Optional pin that allows you to override all tri-states on the device. When this pin is driven low, all I/O pins are tri-stated; when this pin is driven high, all I/O pins behave as programmed. This pin is enabled by turning on the **Enable device-wide output enable (DEV_OE)** option in the Quartus II software.
DEV_CLRn	N/A if option is on. I/O if option is off.	Input	Optional pin that allows you to override all clears on all device registers. When this pin is driven low, all registers are cleared; when this pin is driven high, all registers behave as programmed. You can enable this pin by turning on the **Enable device-wide reset (DEV_CLRn)** option in the Quartus II software.

Document Revision History

Table 9–8 lists the revision history for this chapter.

Table 9–8. Document Revision History

Date	Version	Changes
May 2013	1.3	Updated “CRC_ERROR Pin Type” in Table 9–2.
October 2012	1.2	Updated Table 9–2.
February 2010	1.1	Updated for the Quartus II software version 9.1 SP1 release: ■ Updated “Configuration Error Detection” section. ■ Updated Table 9–6. ■ Added Cyclone IV E devices in Table 9–6.
November 2009	1.0	Initial release.

Cyclone IV Device Handbook,

Volume 2

101 Innovation Drive
San Jose, CA 95134
www.altera.com

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Section I. Transceivers

This section provides a complete overview of all features relating to the Cyclone® IV device transceivers. This section includes the following chapters:

- Chapter 1, Cyclone IV Transceivers Architecture
- Chapter 2, Cyclone IV Reset Control and Power Down
- Chapter 3, Cyclone IV Dynamic Reconfiguration

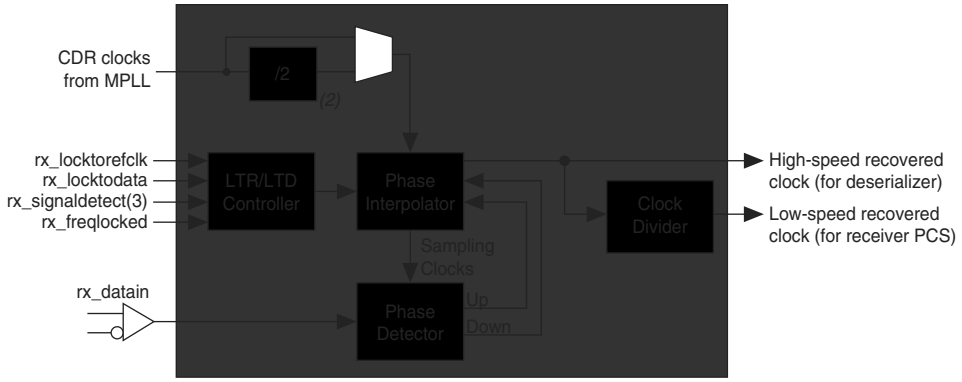
Revision History

Refer to the chapter for its own specific revision history. For information about when the chapter was updated, refer to the Chapter Revision Dates section, which appears in the complete handbook.

Clock Data Recovery

Each receiver channel has an independent CDR unit to recover the clock from the incoming serial data stream. The high-speed recovered clock is used to clock the deserializer for serial-to-parallel conversion of the received input data, and low-speed recovered clock to clock the receiver PCS blocks. Figure 1–15 illustrates the CDR unit block diagram.

Figure 1–15. CDR Unit Block Diagram



Notes to Figure 1–15:

(1) Optional RX local divider for CDR clocks from multipurpose PLL is only available in each CDR unit for EP4CGX30 (F484 package), EP4CGX50, and EP4CGX75 devices. This block is used with the transceiver dynamic reconfiguration feature. For more information, refer to the *Cyclone IV Dynamic Reconfiguration* chapter and *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices*.

(2) CDR state transition in automatic lock mode is not dependent on `rx_signaldetect` signal, except when configured in PCI Express (PIPE) mode only.

Each CDR unit gets the reference clock from one of the two multipurpose phase-locked loops (PLLs) adjacent to the transceiver block. The CDR works by tracking the incoming data with a phase detector and finding the optimum sampling clock phase from the phase interpolator unit. The CDR operations are controlled by the LTR/LTD controller block, where the CDR may operate in the following states:

- Lock-to-reference (LTR) state—phase detector disabled and CDR ignores incoming data
- Lock-to-data (LTD) state—phase detector enabled and CDR tracks incoming data to find the optimum sampling clock phase

State transitions are supported with automatic lock mode and manual lock mode.

Automatic Lock Mode

Upon receiver power-up and reset cycle, the CDR is put into LTR state. Transition to the LTD state is performed automatically when both of the following conditions are met:

- Signal detection circuitry indicates the presence of valid signal levels at the receiver input buffer. This condition is valid for PCI Express (PIPE) mode only. CDR transitions are not dependent on signal detection circuitry in other modes.
- The recovered clock is within the configured part per million (ppm) frequency threshold setting with respect to the CDR clocks from multipurpose PLL.

In configuration with rate match FIFO, the transmitter datapath clocking is identical to Transmitter Only operation as shown in Figure 1–38. In each bonded receiver channel, the CDR unit recovers the clock from serial received data and generates the high- and low-speed recovered clock for each bonded channel. The high-speed recovered clock feeds the channel's deserializer, and low-speed recovered clock is forwarded to receiver PCS. The individual low-speed recovered clock feeds to the following blocks in the receiver PCS:

- word aligner
- write clock of rate match FIFO

The common bonded low-speed clock that is used in all bonded transmitter PCS datapaths feeds the following blocks in each bonded receiver PCS:

- read clock of rate match FIFO
- 8B/10B decoder
- write clock of byte deserializer
- byte ordering
- write clock of RX phase compensation FIFO

When the byte deserializer is enabled, the common bonded low-speed clock frequency is halved before feeding to the write clock of RX phase compensation FIFO. The common bonded low-speed clock is available in FPGA fabric as `coreclkout` port, which can be used in FPGA fabric to send transmitter data and control signals, and capture receiver data and status signals from the bonded channels.

FPGA Fabric-Transceiver Interface Clocking

The FPGA fabric-transceiver interface clocks consists of clock signals from the FPGA fabric to the transceiver blocks, and from the transceiver blocks to the FPGA fabric. These clock resources use the global clock networks (GCLK) in the FPGA core.

For information about the GCLK resources in the Cyclone IV GX devices, refer to *Clock Networks and PLLs in Cyclone IV Devices* chapter.

Table 1–11 lists the FPGA fabric-transceiver interface clocks.

Table 1–11. FPGA Fabric-Transceiver Interface Clocks (Part 1 of 2)

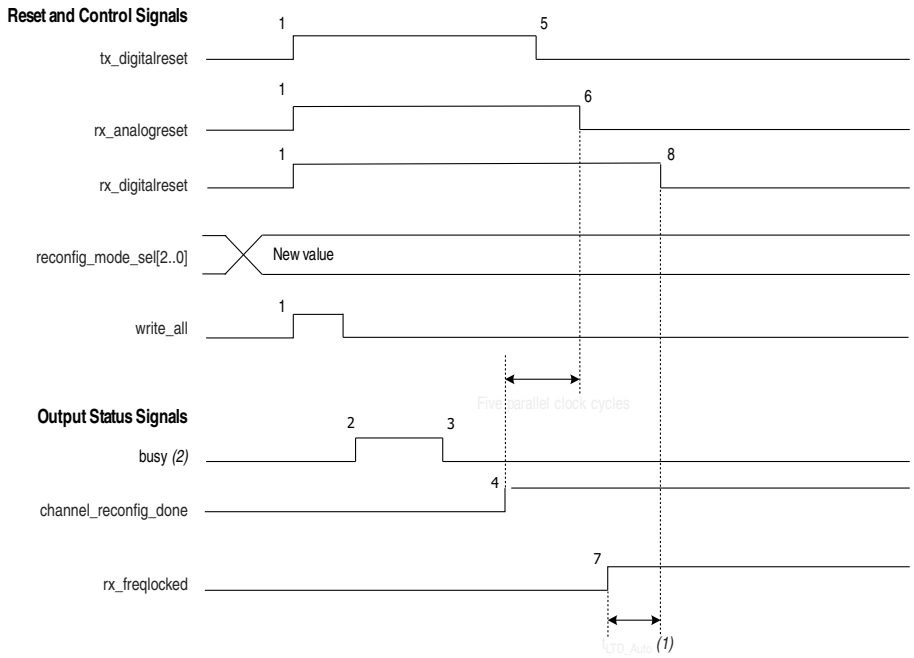
Clock Name	Clock Description	Interface Direction
tx_clkout	Phase compensation FIFO clock	Transceiver to FPGA fabric
rx_clkout	Phase compensation FIFO clock	Transceiver to FPGA fabric
coreclkout	Phase compensation FIFO clock	Transceiver to FPGA fabric
fixed_clk	125MHz receiver detect clock in PIPE mode	FPGA fabric to transceiver
reconfig_clk (1), (2)	Transceiver dynamic reconfiguration and offset cancellation clock	FPGA fabric to transceiver

2. After the PLL is reset, wait for the `pll_locked` signal to go high (marker 4) indicating that the PLL is locked to the input reference clock. After the assertion of the `pll_locked` signal, deassert the `tx_digitalreset` signal (marker 5).
3. Wait at least five parallel clock cycles after the `pll_locked` signal is asserted to deassert the `rx_analogreset` signal (marker 6).
4. When the `rx_freqlocked` signal goes high (marker 7), from that point onwards, wait for at least t_{LTD_Auto} time, then deassert the `rx_digitalreset` signal (marker 8). At this point, the receiver is ready for data traffic.

Reset Sequence in Channel Reconfiguration Mode

Use the example reset sequence shown in Figure 2–12 when you are using the dynamic reconfiguration controller to change the PCS settings of the transceiver channel. In this example, the dynamic reconfiguration is used to dynamically reconfigure the transceiver channel configured in Basic ×1 mode with receiver CDR in automatic lock mode.

Figure 2–12. Reset Sequence When Using the Dynamic Reconfiguration Controller to Change the PCS Settings of the Transceiver Channel



Notes to Figure 2–12:

(1) For t_{LTD_Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.

(2) The `busy` signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the `busy` signal is asserted and deasserted only if there is a read or write operation to the ALTGX_RECONFIG megafunction.

As shown in Figure 2–12, perform the following reset procedure when using the dynamic reconfiguration controller to change the configuration of the transceiver channel:

1. After power up and establishing that the transceiver is operating as desired, write the desired new value in the appropriate registers (including `reconfig_mode_sel[2:0]`) and subsequently assert the `write_all` signal (marker 1) to initiate the dynamic reconfiguration.

   For more information, refer to the *Cyclone IV Dynamic Reconfiguration* chapter.

2. Assert the `tx_digitalreset`, `rx_analogreset`, and `rx_digitalreset` signals.
3. As soon as `write_all` is asserted, the dynamic reconfiguration controller starts to execute its operation. This is indicated by the assertion of the `busy` signal (marker 2).
4. Wait for the assertion of the `channel_reconfig_done` signal (marker 4) that indicates the completion of dynamic reconfiguration in this mode.
5. Deassert the `tx_digitalreset signal` (marker 5). This signal must be deasserted after assertion of the `channel_reconfig_done` signal (marker 4) and before the deassertion of the `rx_analogreset` signal (marker 6).
6. Wait for at least five parallel clock cycles after assertion of the `channel_reconfig_done` signal (marker 4) to deassert the `rx_analogreset` signal (marker 6).
7. Lastly, wait for the `rx_freqlocked` signal to go high. After `rx_freqlocked` goes high (marker 7), wait for t_{LTD_Auto} to deassert the `rx_digitalreset` signal (marker 8). At this point, the receiver is ready for data traffic.

Power Down

The Quartus II software automatically selects the power-down channel feature, which takes effect when you configure the Cyclone IV GX device. All unused transceiver channels and blocks are powered down to reduce overall power consumption. The `gxb_powerdown` signal is an optional transceiver block signal. It powers down all transceiver channels and all functional blocks in the transceiver block. The minimum pulse width for this signal is 1 µs. After power up, if you use the `gxb_powerdown` signal, wait for deassertion of the `busy` signal, then assert the `gxb_powerdown` signal for a minimum of 1 µs. Lastly, follow the sequence shown in Figure 2–13.

Control and Status Signals for Channel Reconfiguration

The various control and status signals involved in the Channel Reconfiguration mode are as follows. Refer to "Dynamic Reconfiguration Controller Port List" on page 3–4 for the descriptions of the control and status signals.

The following are the input control signals:

- `logical_channel_address[n..0]`
- `reset_reconfig_address`
- `reconfig_reset`
- `reconfig_mode_sel[2..0]`
- `write_all`

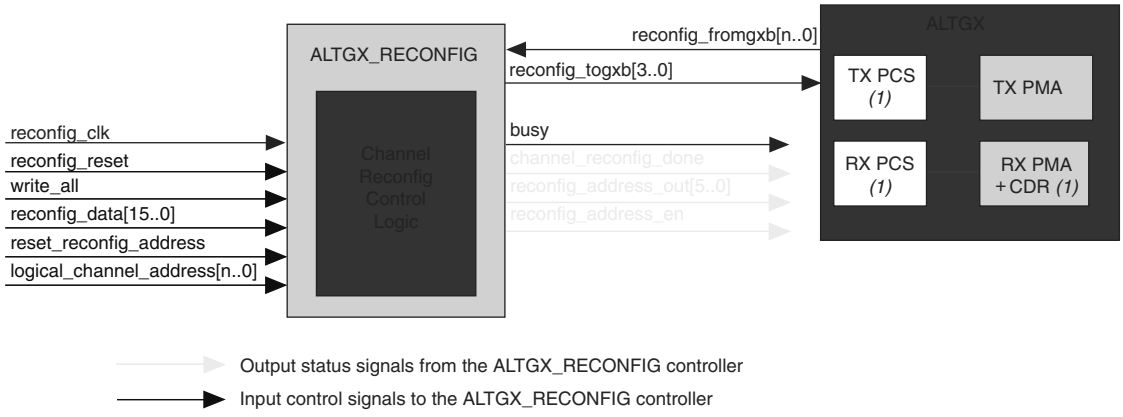
The following are output status signals:

- `reconfig_address_en`
- `reconfig_address_out[5..0]`
- `channel_reconfig_done`
- `busy`

The ALTGX_RECONFIG connection to the ALTGX instances when set in channel reconfiguration mode are as follows. For the port information, refer to "Dynamic Reconfiguration Controller Port List" on page 3–4.

Figure 3–10 shows the connection for channel reconfiguration mode.

Figure 3–10. ALTGX and ALTGX_RECONFIG Connection for Channel Reconfiguration Mode



Note to Figure 3–10:

(1) This block can be reconfigured in channel reconfiguration mode.

Visual Cue	Meaning
`Courier type`	Indicates signal, port, register, bit, block, and primitive names. For example, `data1`, `tdi`, and `input`. The suffix `n` denotes an active-low signal. For example, `resetn`. Indicates command line commands and anything that must be typed exactly as it appears. For example, `c:\qdesigns\tutorial\chiptrip.gdf`. Also indicates sections of an actual file, such as a Report File, references to parts of files (for example, the AHDL keyword `SUBDESIGN`), and logic function names (for example, `TRI`).
↵	An angled arrow instructs you to press the Enter key.
1., 2., 3., and a., b., c., and so on	Numbered steps indicate a list of items when the sequence of the items is important, such as the steps listed in a procedure.
■ ■ ■	Bullets indicate a list of items when the sequence of the items is not important.
	The hand points to information that requires special attention.
	The question mark directs you to a software help system with related information.
	The feet direct you to another document or website with related information.
	The multimedia icon directs you to a related multimedia presentation.
	A caution calls attention to a condition or possible situation that can damage or destroy the product or your work.
	A warning calls attention to a condition or possible situation that can cause you injury.
	The envelope links to the Email Subscription Management Center page of the Altera website, where you can sign up to receive update notifications for Altera documents.

DC Characteristics

This section lists the I/O leakage current, pin capacitance, on-chip termination (OCT) tolerance, and bus hold specifications for Cyclone IV devices.

Supply Current

The device supply current requirement is the minimum current drawn from the power supply pins that can be used as a reference for power size planning. Use the Excel-based early power estimator (EPE) to get the supply current estimates for your design because these currents vary greatly with the resources used. Table 1–6 lists the I/O pin leakage current for Cyclone IV devices.

Table 1–6. I/O Pin Leakage Current for Cyclone IV Devices *(1), (2)*

Symbol	Parameter	Conditions	Device	Min	Typ	Max	Unit
I_I	Input pin leakage current	V_I = 0 V to $V_{CCIOMAX}$	—	–10	—	10	µA
I_{OZ}	Tristated I/O pin leakage current	V_O = 0 V to $V_{CCIOMAX}$	—	–10	—	10	µA

Notes to Table 1–6:

(1) This value is specified for normal device operation. The value varies during device power-up. This applies for all V_{CCIO} settings (3.3, 3.0, 2.5, 1.8, 1.5, and 1.2 V).

(2) The 10 µA I/O leakage current limit is applicable when the internal clamping diode is off. A higher current can be observed when the diode is on.

Bus Hold

The bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1–7 lists bus hold specifications for Cyclone IV devices.

Table 1–7. Bus Hold Parameter for Cyclone IV Devices (Part 1 of 2) *(1)*

Parameter	Condition	V_{CCIO} (V)												Unit
		1.2		1.5		1.8		2.5		3.0		3.3		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold low, sustaining current	$V_{IN} > V_{IL}$ (maximum)	8	—	12	—	30	—	50	—	70	—	70	—	µA
Bus hold high, sustaining current	$V_{IN} < V_{IL}$ (minimum)	–8	—	–12	—	–30	—	–50	—	–70	—	–70	—	µA
Bus hold low, overdrive current	0 V < V_{IN} < V_{CCIO}	—	125	—	175	—	200	—	300	—	500	—	500	µA
Bus hold high, overdrive current	0 V < V_{IN} < V_{CCIO}	—	–125	—	–175	—	–200	—	–300	—	–500	—	–500	µA

For more information about receiver input and transmitter output waveforms, and for other differential I/O standards, refer to the *I/O Features in Cyclone IV Devices* chapter.

Table 1–18. Differential SSTL I/O Standard Specifications for Cyclone IV Devices (1)

I/O Standard	V_{CCIO} (V)			$V_{Swing(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{Swing(AC)}$ (V)		$V_{OX(AC)}$ (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.36	V_{CCIO}	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.7	V_{CCIO}	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$
SSTL-18 Class I, II	1.7	1.8	1.90	0.25	V_{CCIO}	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	V_{CCIO}	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$

Note to Table 1–18:

(1) Differential SSTL requires a V_{REF} input.

Table 1–19. Differential HSTL I/O Standard Specifications for Cyclone IV Devices (1)

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.85	—	0.95	0.85	—	0.95	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.71	—	0.79	0.71	—	0.79	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V_{CCIO}	$0.48 \times V_{CCIO}$	—	$0.52 \times V_{CCIO}$	$0.48 \times V_{CCIO}$	—	$0.52 \times V_{CCIO}$	0.3	$0.48 \times V_{CCIO}$

Note to Table 1–19:

(1) Differential HSTL requires a V_{REF} input.

Table 1–20. Differential I/O Standard Specifications for Cyclone IV Devices (1) (Part 1 of 2)

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)		V_{ICM} (V) (2)			V_{OD} (mV) (3)			V_{OS} (V) (3)		
	Min	Typ	Max	Min	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
LVPECL (Row I/Os) (6)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq 500$ Mbps	1.80	—	—	—	—	—	—
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						
LVPECL (Column I/Os) (6)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	—	—	—	—	—	—
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						
LVDS (Row I/Os)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	247	—	600	1.125	1.25	1.375
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						

Table 1–24. Clock Tree Performance for Cyclone IV Devices *(Part 2 of 2)*

Device	Performance								Unit
	C6	C7	C8	C8L (1)	C9L (1)	I7	I8L (1)	A7	
EP4CE55	500	437.5	402	362	265	437.5	362	—	MHz
EP4CE75	500	437.5	402	362	265	437.5	362	—	MHz
EP4CE115	—	437.5	402	362	265	437.5	362	—	MHz
EP4CGX15	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX22	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX30	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX50	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX75	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX110	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX150	500	437.5	402	—	—	437.5	—	—	MHz

Note to Table 1–24:

(1) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades.

PLL Specifications

Table 1–25 lists the PLL specifications for Cyclone IV devices when operating in the commercial junction temperature range (0°C to 85°C), the industrial junction temperature range (–40°C to 100°C), the extended industrial junction temperature range (–40°C to 125°C), and the automotive junction temperature range (–40°C to 125°C). For more information about the PLL block, refer to "Glossary" on page 1–37.

Table 1–25. PLL Specifications for Cyclone IV Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
f_{IN} (3)	Input clock frequency (–6, –7, –8 speed grades)	5	—	472.5	MHz
	Input clock frequency (–8L speed grade)	5	—	362	MHz
	Input clock frequency (–9L speed grade)	5	—	265	MHz
f_{INPFD}	PFD input frequency	5	—	325	MHz
f_{VCO} (4)	PLL internal VCO operating range	600	—	1300	MHz
f_{INDUTY}	Input clock duty cycle	40	—	60	%
$t_{INJITTER\_CCJ}$ (5)	Input clock cycle-to-cycle jitter $F_{REF} \geq 100$ MHz	—	—	0.15	UI
	$F_{REF} < 100$ MHz	—	—	±750	ps
f_{OUT_EXT} (external clock output) (3)	PLL output frequency	—	—	472.5	MHz
f_{OUT} (to global clock)	PLL output frequency (–6 speed grade)	—	—	472.5	MHz
	PLL output frequency (–7 speed grade)	—	—	450	MHz
	PLL output frequency (–8 speed grade)	—	—	402.5	MHz
	PLL output frequency (–8L speed grade)	—	—	362	MHz
	PLL output frequency (–9L speed grade)	—	—	265	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	45	50	55	%
t_{LOCK}	Time required to lock from end of device configuration	—	—	1	ms

Document Revision History

Table 1–47 lists the revision history for this chapter.

Table 1–47. Document Revision History

Date	Version	Changes
December 2016	2.1	Added note to Table 1–9 and Table 1–10.
March 2016	2.0	Updated note (5) in Table 1–21 to remove support for the N148 package.
October 2014	1.9	Updated maximum value for V_{CCD_PLL} in Table 1–1. Removed extended temperature note in Table 1–3.
December 2013	1.8	Updated Table 1–21 by adding Note (15).
May 2013	1.7	Updated Table 1–15 by adding Note (4).
October 2012	1.6	■ Updated the maximum value for V_I, V_{CCD_PLL}, V_{CCIO}, V_{CC_CLKIN}, V_{CCH_GXB}, and V_{CCA_GXB} Table 1–1. ■ Updated Table 1–11 and Table 1–22. ■ Updated Table 1–21 to include peak-to-peak differential input voltage for the Cyclone IV GX transceiver input reference clock. ■ Updated Table 1–29 to include the typical DCLK value. ■ Updated the minimum f_{HSCLK} value in Table 1–31, Table 1–32, Table 1–33, Table 1–34, and Table 1–35.
November 2011	1.5	■ Updated “Maximum Allowed Overshoot or Undershoot Voltage”, “Operating Conditions”, and “PLL Specifications” sections. ■ Updated Table 1–2, Table 1–3, Table 1–4, Table 1–5, Table 1–8, Table 1–9, Table 1–15, Table 1–18, Table 1–19, and Table 1–21. ■ Updated Figure 1–1.
December 2010	1.4	■ Updated for the Quartus II software version 10.1 release. ■ Updated Table 1–21 and Table 1–25. ■ Minor text edits.
July 2010	1.3	Updated for the Quartus II software version 10.0 release: ■ Updated Table 1–3, Table 1–4, Table 1–21, Table 1–25, Table 1–28, Table 1–30, Table 1–40, Table 1–41, Table 1–42, Table 1–43, Table 1–44, and Table 1–45. ■ Updated Figure 1–2 and Figure 1–3. ■ Removed SW Requirement and TCCS for Cyclone IV Devices tables. ■ Minor text edits.
March 2010	1.2	Updated to include automotive devices: ■ Updated the “Operating Conditions” and “PLL Specifications” sections. ■ Updated Table 1–1, Table 1–8, Table 1–9, Table 1–21, Table 1–26, Table 1–27, Table 1–31, Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–36, Table 1–37, Table 1–38, Table 1–40, Table 1–42, and Table 1–43. ■ Added Table 1–5 to include ESD for Cyclone IV devices GPIOs and HSSI I/Os. ■ Added Table 1–44 and Table 1–45 to include IOE programmable delay for Cyclone IV E 1.2 V core voltage devices. ■ Minor text edits.